2081570-2 - ACTIVE

TE Internal #: 2081570-2 OS 2.9 RF Interface, Jack, 50 Ω, Screw, 40 GHz Operating Frequency, Cable-to-Board, 1 Position, Printed Circuit Board, -55 – 125 °C [-67 – 257 °F]

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Connectors > RF Connectors > RF Plugs & Jacks



RF Interface: OS 2.9

RF Connector Style: Jack

Impedance: 50Ω

RF Connector Coupling Mechanism: Screw

Operating Frequency: 40 GHz

Features

Product Type Features

RF Interface	OS 2.9	
RF Connector Style	Jack	
Connector System	Cable-to-Board	
Sealable	No	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
PCB Mount Orientation	Vertical	
Number of Positions	1	
Number of Coaxial Contacts	1	
Electrical Characteristics		
EMI & RFI Protection & Suppression Type	PCB Ground	
Impedance	50 Ω	
Body Features		
Cable Connector Orientation	Straight	

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Body Material	Stainless Steel	
Body Material Finish	Passivated	
Contact Features		
RF Connector Center Contact Plating Material	Gold	
RF Connector Center Contact Material	Beryllium Copper	
Mechanical Attachment		
RF Connector Coupling Mechanism	Screw	
Dimensions		
Profile Height from PCB	9.6 mm[.378 in]	
Usage Conditions		
Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]	
Operation/Application		
Operating Frequency	40 GHz	
Circuit Application	Power & Signal	
Packaging Features		
Packaging Method	Bag	

Other



Dielectric Material

Polyetherimide (PEI)

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant with Exemptions	
EU ELV Directive 2000/53/EC	Not Yet Reviewed	
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold	
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2023 (233) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC	
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free	
Solder Process Capability	Not reviewed for solder process capability	

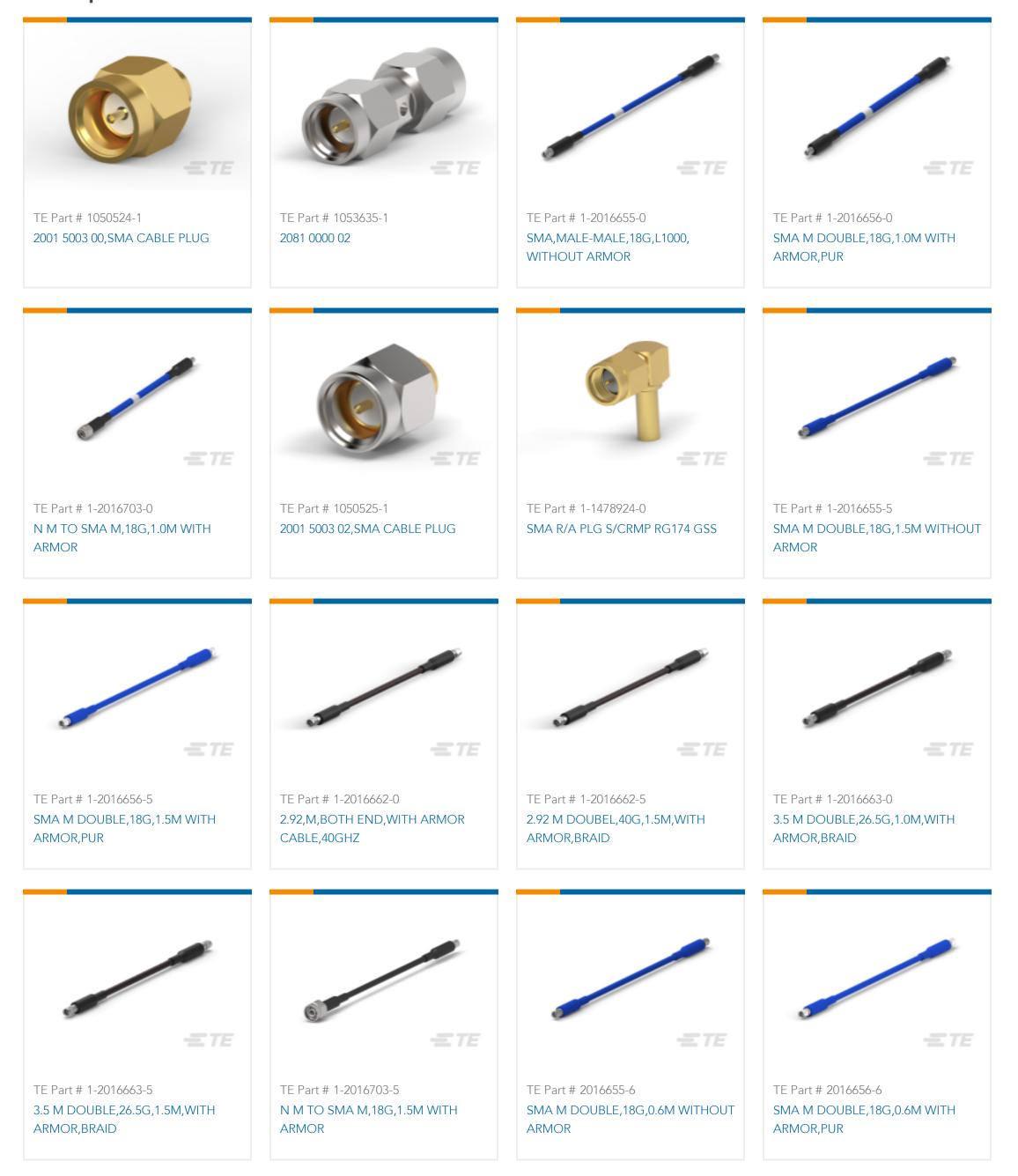
OS 2.9 RF Interface, Jack, 50 Ω, Screw, 40 GHz Operating Frequency, Cable-to-Board, 1 Position, Printed Circuit Board, -55 – 125 °C [-67 – 257 °F]



Product Compliance Disclaimer

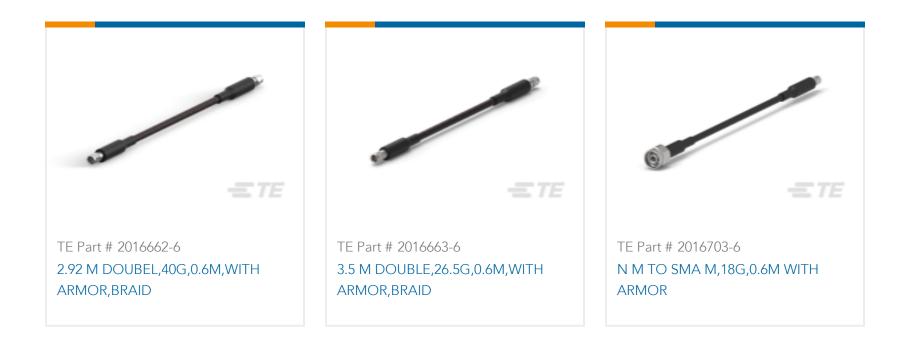
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

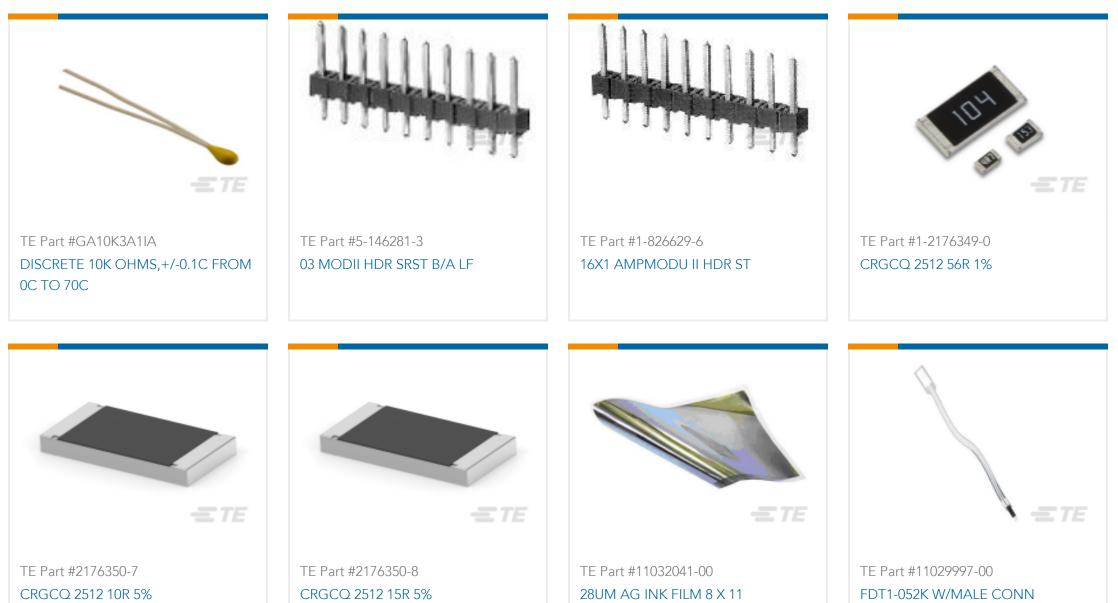


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Customers Also Bought



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= <i>TE</i>		
TE Part #11028362-00 LDT0-028K W/SOLDER TAB CLEAR		

Documents

Product Drawings 2.92MM JACK 2 HOLE FLANGE RECEPTACLE

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2081570-2_A.2d_dxf.zip

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English
Customer View Model

ENG_CVM_CVM_2081570-2_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2081570-2_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Product Specification

English